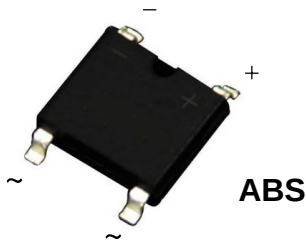
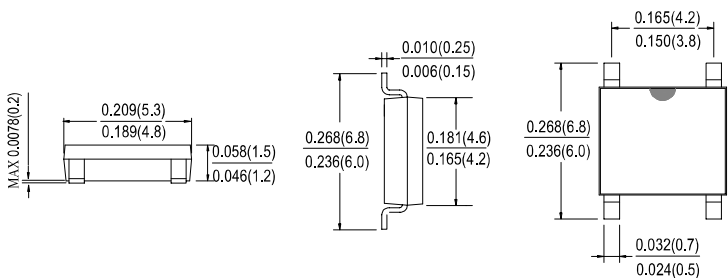


FEATURES

- UL Recognized Component
- High surge current capability
- Ideal for Printed Circuit Board
- Plastic Package - UL Flammability Classification 94V-0

**MECHANICAL DATA**

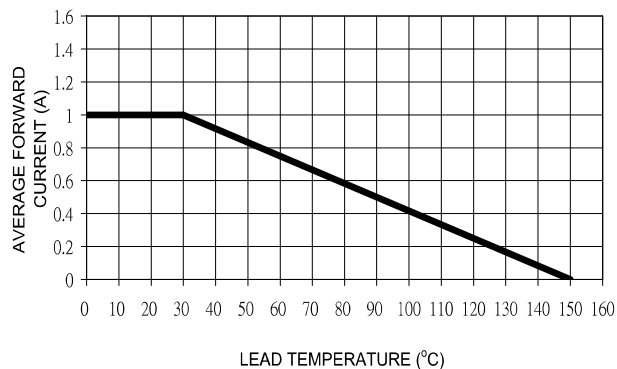
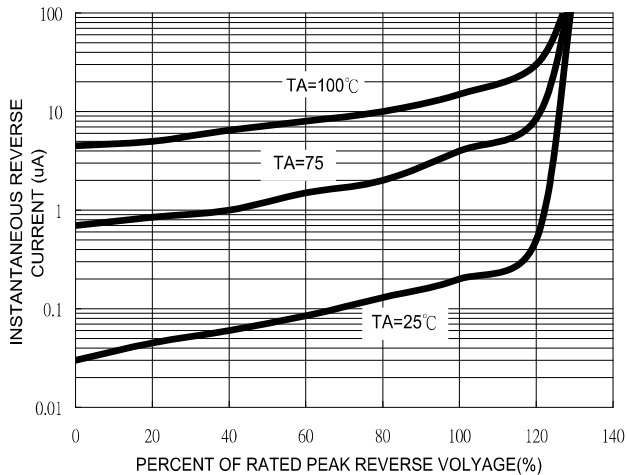
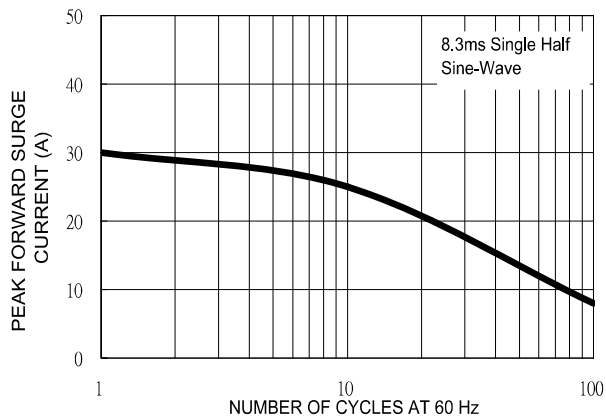
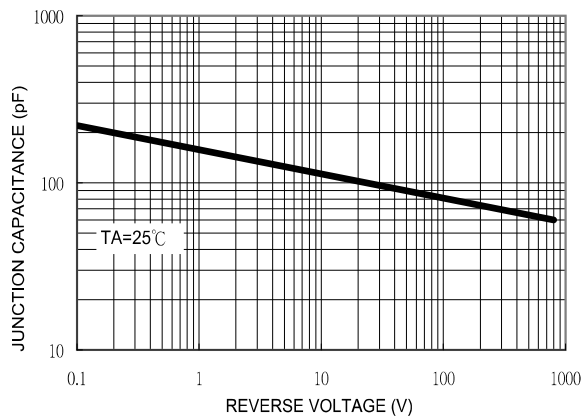
- Case: Transfer Molded Epoxy
- Mounting Position: Any
- Terminals: Plated leads solderable per MTL-STD-750, Method 2026

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%

Characteristic		Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	Unit
Maximum Repetitive Peak Reverse Voltage		V _{RRM}	200	400	600	800	1000	V
Maximum RMS Voltage		V _{RMS}	140	280	420	560	700	V
Maximum DC Blocking Voltage		V _{DC}	200	400	600	800	1000	V
Average Rectified Output Current @T _A =40°C		I _{F(AV)}	1.0					A
Peak Forward Surge Current, 8.3 ms Single Half Sine- wave Superimposed on Rated Load (JEDEC method)		I _{FSM}	30					A
Forward Voltage drop per Element at I _F = 1.0A		V _F	1.1					V
Rating for fusing (t<8.3mS)		I ² T	3.74					A ² sec
Peak Reverse Current At Rated DC Blocking Voltage	T _A =25°C T _A =125°C	I _R	10 150					μA
Typical Thermal Resistance (Note 1)		R _{θJL} R _{θJA}	25 80					°C/W
Storage and Operating Temperature Range		T _J , T _{STG}	- 55 to + 150					°C

Notes: (1) Thermal resistance from Junction to Ambient on PC board mounting.

Typical Characteristics**FIG. 1 MAXIMUM FORWARD CURRENT DERATING CURVE****FIG. 2 TYPICAL REVERSE CHARACTERISTICS****FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT****FIG. 4 TYPICAL JUNCTION CAPACITANCE****FIG. 5 TYPICAL FORWARD CHARACTERISTICS**